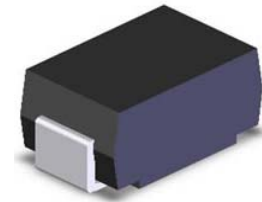


**特征 FEATURES**

- 低的反向漏电流 Low reverse leakage  
较强的正向浪涌承受能力 High forward surge capability
- 高温焊接保证 High temperature soldering guaranteed:  
250°C/10 秒 seconds at terminals

**机械数据 Mechanical Date**

- 封装: 塑料封装
- 端子: 焊料被镀
- 极性: 色环端为负极
- 安装位置: 任意
- Case: JEDEC DO-214AC molded plastic body.
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position: Any
- Polarity: Laser band denotes cathode end
- Weight: 0.002 ounce, 0.07 grams



SMA (DO-214AC)

**Major Ratings and Characteristics**

$I_{F(AV)}$	1.0 A
$V_{RRM}$	50V to 1000V
$I_{FSM}$	20 A
$V_F$	1.1 V
$T_j(\text{max.})$	125°C

■ Maximum Ratings & Thermal Characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise noted)

Items	Symbol	M1	M2	M3	M4	M5	M6	M7	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	
Maximum average forward rectified current at $T_L=110^\circ\text{C}$	$I_{F(AV)}$	1.0							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load(JEDEC Method)	$I_{FSM}$	20							
Thermal resistance from junction to ambient <sup>(1)</sup>	$R_{\theta JA}$	75							°C/W
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +125							°C

Note 1: Mounted on P.C.B. with  $0.2 \times 0.2$ " ( $5.0 \times 5.0\text{mm}$ ) copper pad areas.

■ Electrical Characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise noted)

Items	Test conditions	Symbol	Min.	Typ.	Max.	UNIT
Instantaneous forward It	$I_F=1.0A$ <sup>(2)</sup>	$V_F$	--	--	1.10	V
Reverse current	$V_R=V_{DC}$	$I_R$	$T_J=25^\circ\text{C}$	--	5	$\mu\text{A}$
			$T_J=100^\circ\text{C}$	--	50	
Typical junction capacitance	4.0V, 1MHz	$C_J$	--	15.0	--	pF

Note 2: Pulse test: 300 $\mu\text{s}$  pulse width, 1% duty cycle.

Characteristic Curves ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Fig 1: FORWARD CURRENT DERATING CURVE

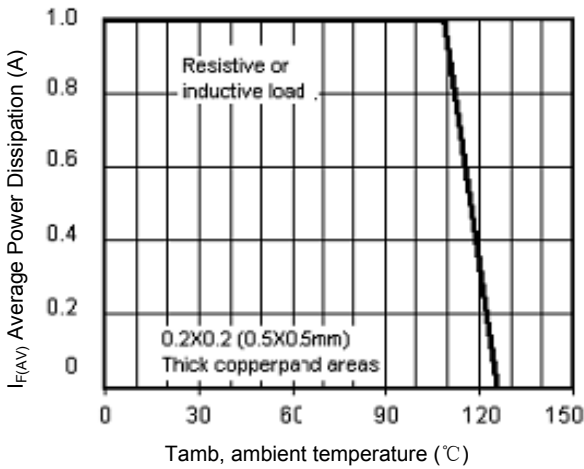


Fig 2: MAXIMUM NON REPETITIVE PEAK FORWARD SURGE CURRENT

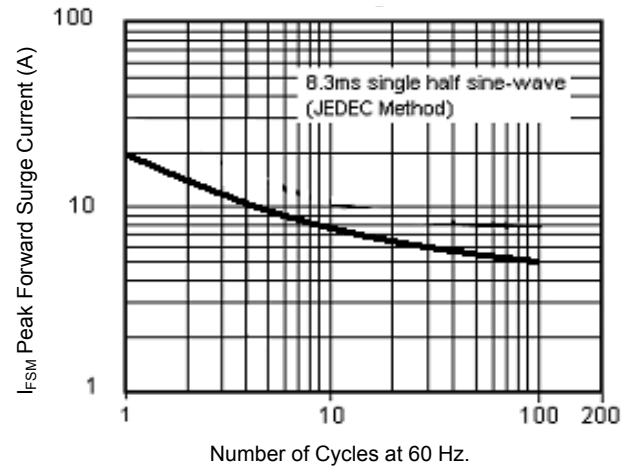


Fig 3: TYPICAL FORWARD CHARACTERISTIC

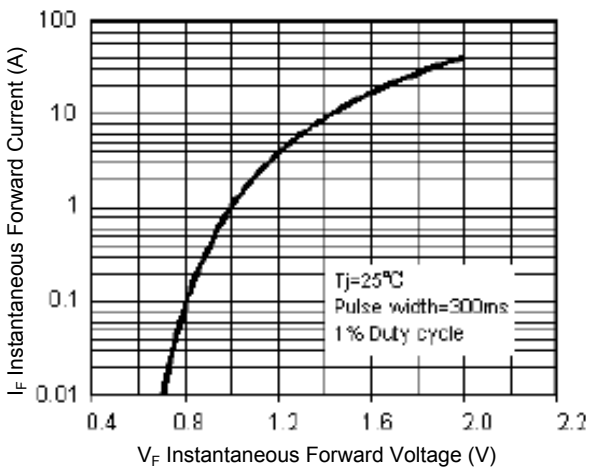


Fig 4: TYPICAL REVERSE CHARACTERISTICS

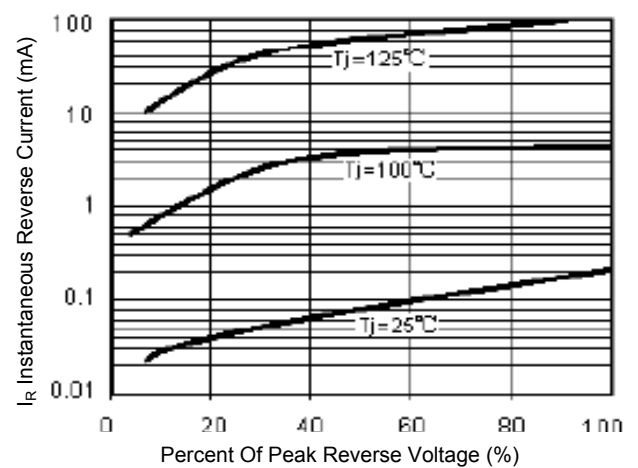


Fig 5: TYPICAL JUNCTION CAPACITANCE

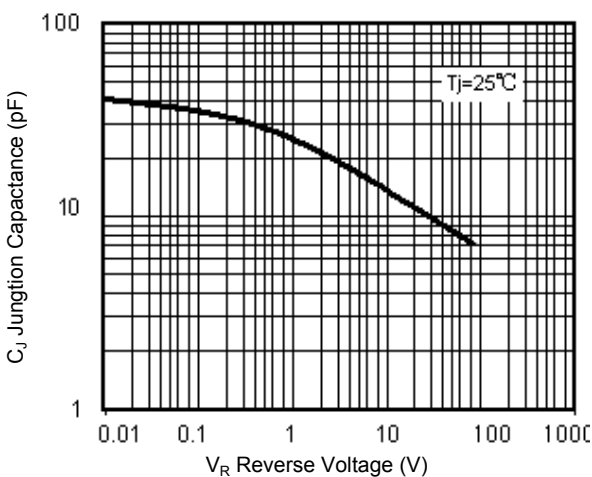
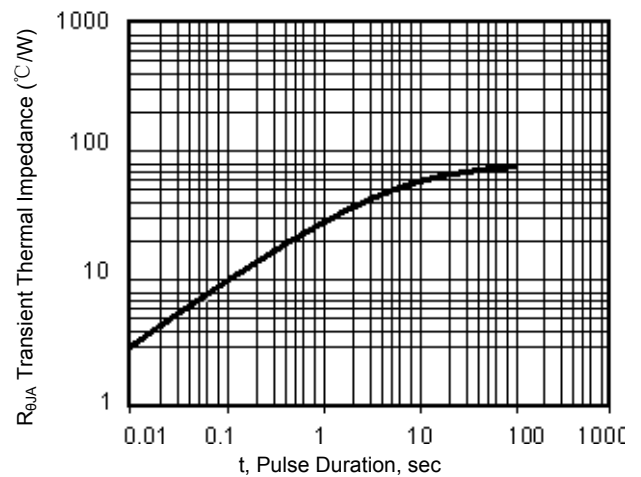
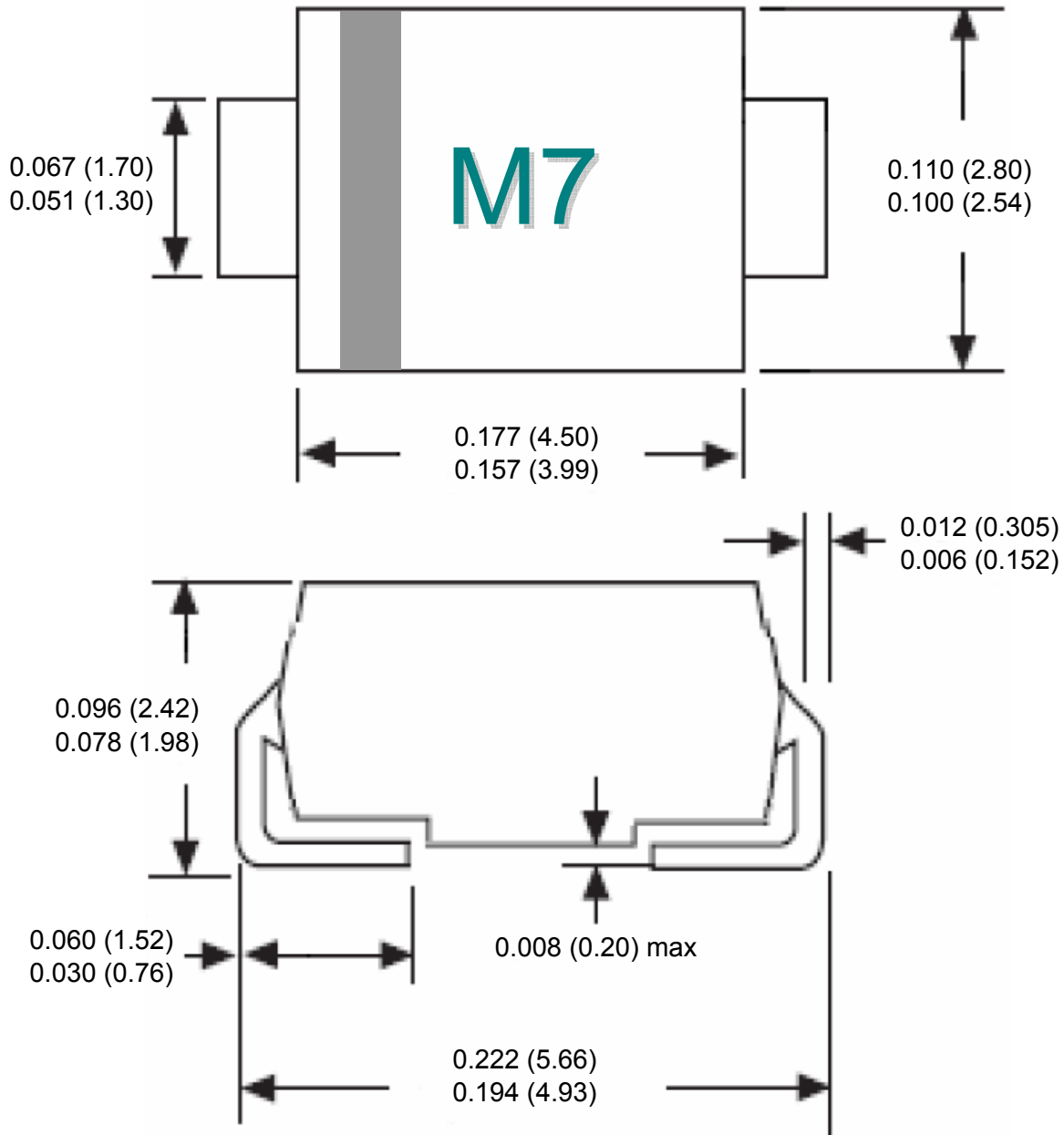


Fig 6: TYPICAL TRANSIENT THERMAL IMPEDANCE



# Package Outline

## SMA DO-214AC



Dimensions in inches and (millimeters)



经中华人民共和国工商行政管理总局商标局批准  
HAOHAI、HHE 图案、字母、均为我公司正式注册商标，仿冒、盗用均属侵权，违法必究！

## 深圳市浩海电子有限公司

**SHENZHEN HAOHAI ELECTRONICS CO., LTD.**

2 floor(whole floor), BAOXIN Building. 0 Lane on the 8th. Yufeng Garden.  
82 District. BAOAN District, Shenzhen City, Guangdong Province, China.

中國 廣東省 深圳市 寶安區 82区 裕豐花園 零巷8號 寶馨樓 二楼(全层)

公司电话 TEL: +86-755-29955080、29955081、29955082、29955083  
总机八线 29955090、29955091、29955092、29955093

FAX: +86-755-27801767

E-mail: [kkg@kkg.com.cn](mailto:kkg@kkg.com.cn)

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